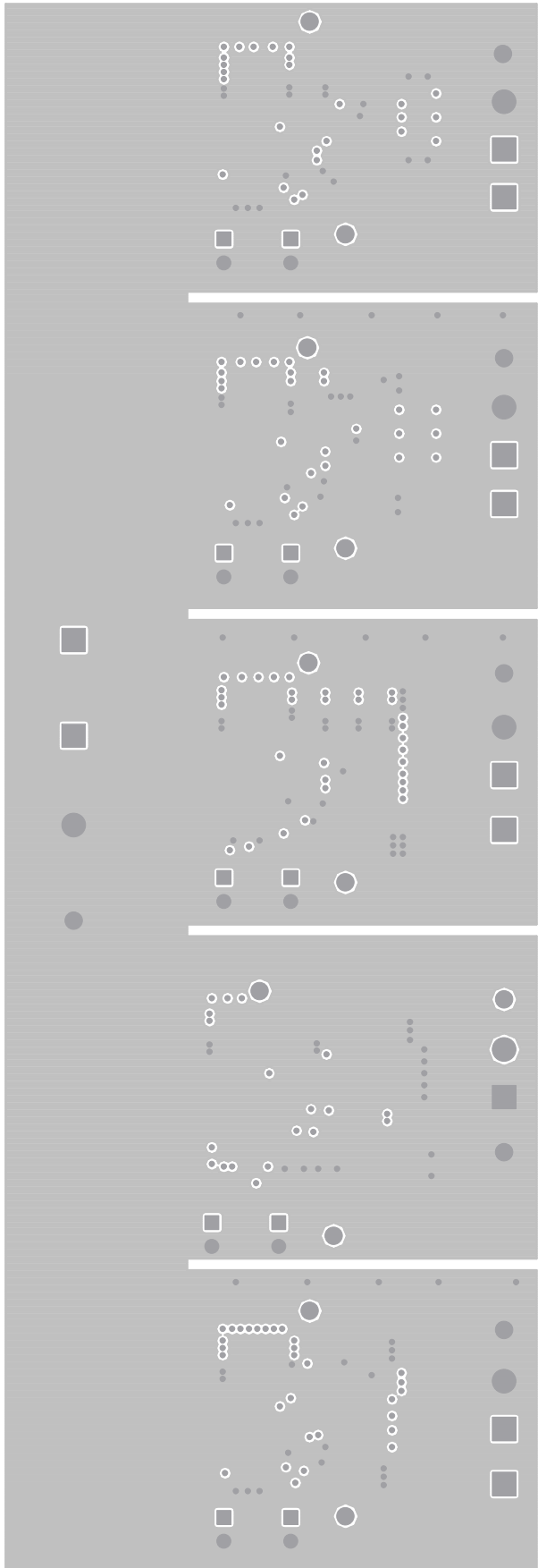


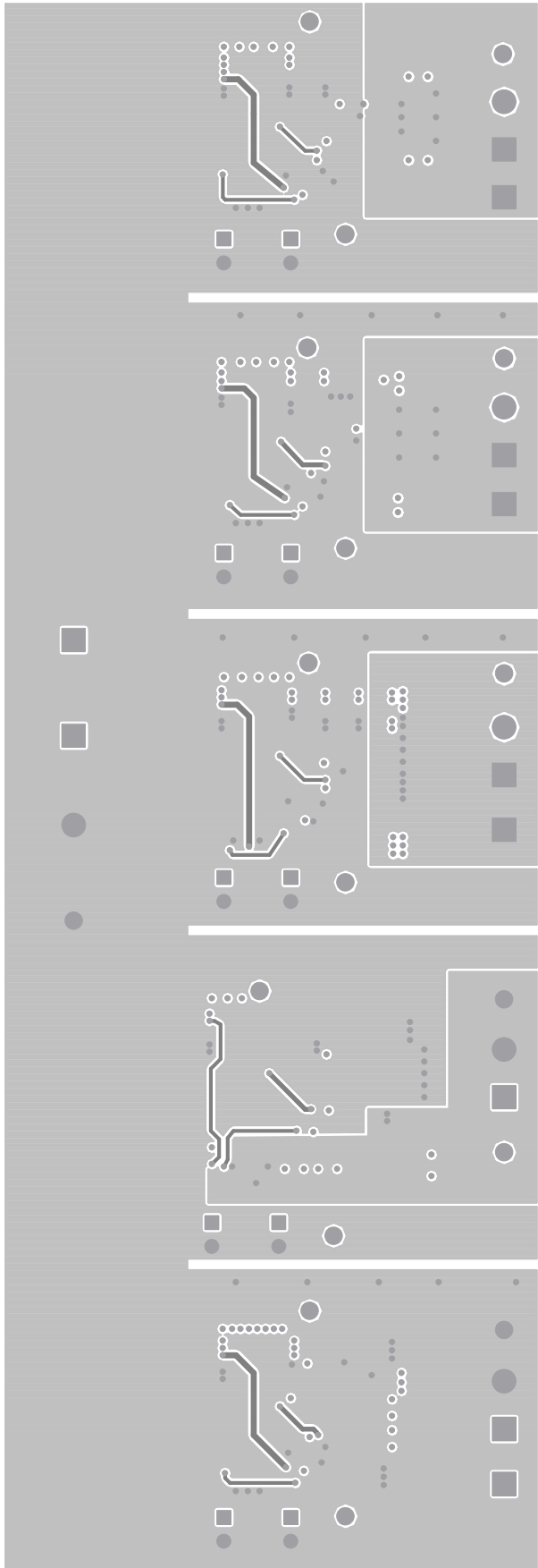
Texas Instruments
PMP5754 REV A

2010

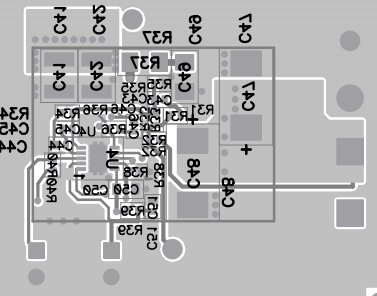
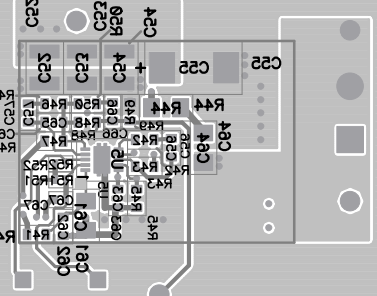
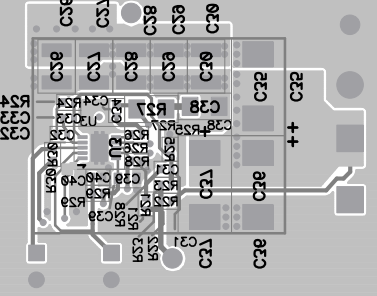
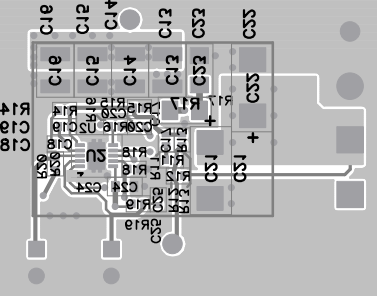
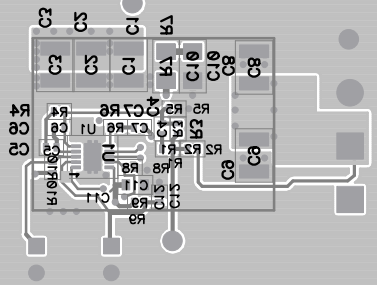
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP5754	Rev. a	L1			S1				TA		
Date: 6/18/10	Filename: PMP5754B_REV_B_PCB.dwg	Engineer: J. Burk	PCB Dsgnr: {Drawn By}	Modified Date: Mon Oct 04, 2010	Time Stamp: 13:02:27						



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP5754	Rev.	a	L2							
Date:	6/18/10	Filename:	PMP5754B_REVb_PCB.dwg	Engineer:	Chris Burk	PCB Dsgnr:	{Drawn By}	Modified Date:	Mon Oct 04, 2010	Time Stamp:	13:02:27



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP5754	Rev.	a	L3							
Date:	6/18/10	Filename:	PMP5754B_REV0_PCB.dwg	Engineer:	Eric Burck	PCB Dsgnr:	{Drawn By}	Modified Date:	Mon Oct 04, 2010	Time Stamp:	13:02:27



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP5754	Rev. a			L4		S4				BA	
Date: 6/18/10	Filename: PMP5754B_REV0_PCB.tbr	Engineer: Brian Burk	PCB Dsgnr: {	Drawn By: }	Modified Date: Mon Oct 04, 2010	Time Stamp: 13:02:27					

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